

# **ABSTRACT**

A method of forming a sputtering target is described that involves bonding a backing plate onto a casement having one or more recesses that contain target material to form a bonded target. During the bonding process, the bonded target is optionally vacuum sealed within the recess. The bonded target is then optionally annealed while under vacuum to form an annealed sputtering target. The sputtering target can then be retrieved by removing at least a portion of the casement from the sputtering target in one or several steps. Also described is a casement having one or more recesses containing bonded target material that is optionally vacuum sealed in the casement. The casement, as well as the backing plate that is optionally bonded onto the casement, are further described as well as other options and methods.